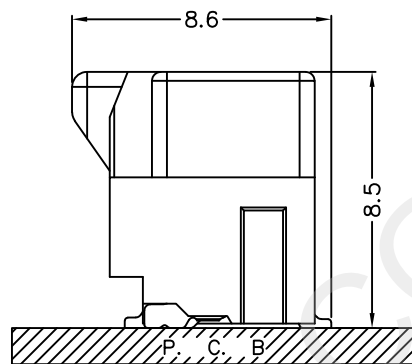
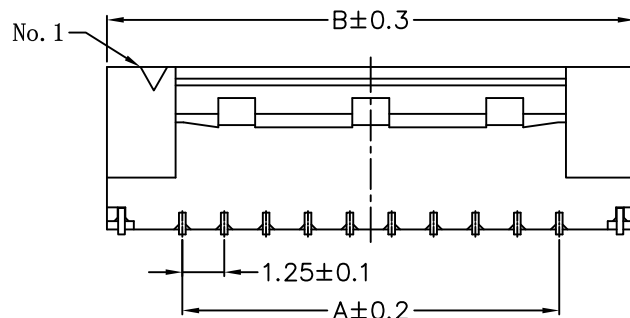
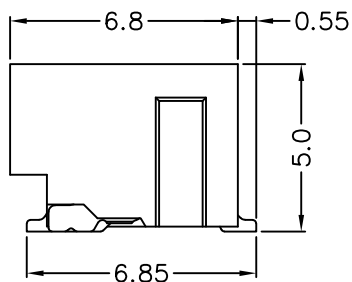
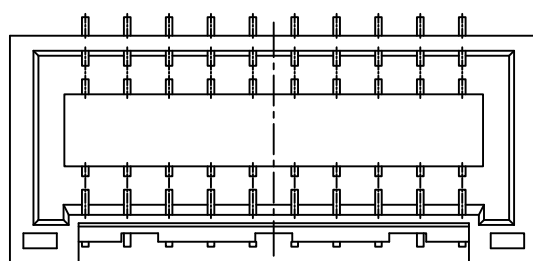
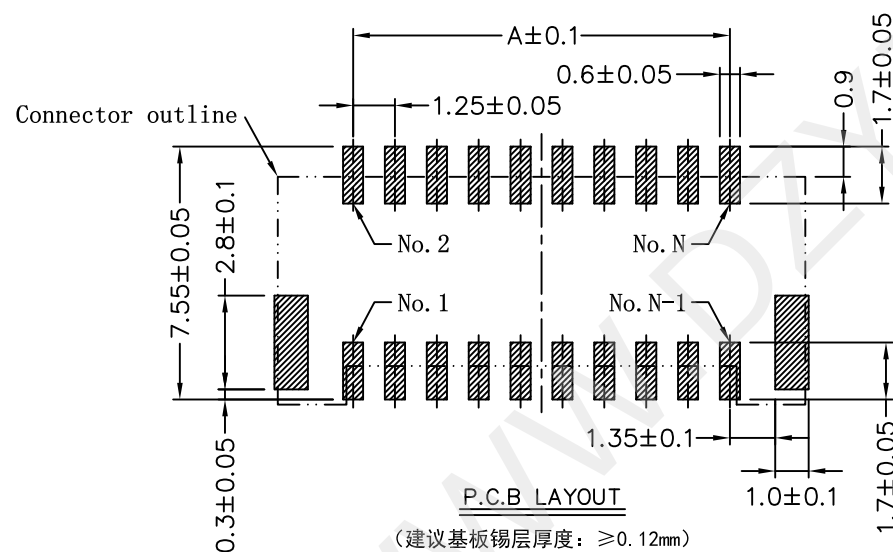




(装 配 图)



(建议基板锡层厚度: ≥0.12mm)

■ 技术参数 SPECIFICATIONS

- ◆ 适用线规: AWG.#26~#32
Applicable Wire: AWG.#26~#32
- ◆ 额定电压: 50V DC/AC(rms)
Rated voltage: 50V DC/AC(rms)
- ◆ 额定电流: 1A (AWG.#26)
Rated Current: 1A (AWG.#26)
- ◆ 耐压值: 500V AC/minute
Withstand voltage: 500V AC/min.
- ◆ 工作温度: -25°C ~ +85°C
Working Temp : -25°C ~ +85°C
- ◆ 绝缘电阻: ≥100 MΩ
Insulation resistance: ≥100 MΩ
- ◆ 接触电阻: ≤30 mΩ
Contact resistance: ≤30 mΩ

■ 材料 MATERIAL

- ◆ 绝缘体: 高温尼龙, UL94-V0
Insulator: Glass-Filled Polyamide, UL94V-0
- ◆ 接触针: 磷铜
Contact PIN: Phosphor Bronze
- ◆ 焊片: 磷铜
Solder tab: Phosphor Bronze

Poles	DIM.A	DIM.B
2x5P	5.00	9.50
2x6P	6.25	10.75
2x7P	7.50	12.00
2x8P	8.75	13.25
2x9P	10.00	14.50
2x10P	11.25	15.75
2x11P	12.50	17.00
2x12P	13.75	18.25
2x13P	15.00	19.50
2x14P	16.25	20.75
2x15P	17.50	22.00
2x16P	18.75	23.25
2x17P	20.00	24.50
2x18P	21.25	25.75
2x19P	22.50	27.00
2x20P	23.75	28.25



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2" X.X' ±0.5"	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 1.25PH 双排 立式贴片WAFER	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYC286-LF2XN-125
 UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	HYC-2601081630
			SHEET NO.	1 OF 1